

WHAT IS CLAIMED IS

1 1. An electronic device comprising:
2 a sealed housing;
3 an electrical circuit component in said sealed
4 housing; and
5 a movable fin that protrudes to the outside of
6 said sealed housing depending on a rise in internal
7 temperature of said sealed housing.

1 2. An electronic device as claimed in claim 1,
2 wherein said movable fin protrudes to the outside of said
3 sealed housing through a guide hole formed in said sealed
4 housing, and has airtightness means between itself and said
5 guide hole.

1 3. An electronic device as claimed in claim 1,
2 wherein a heat generating portion of a package or the like
3 mounted therein with said electrical circuit component and
4 said movable fin are connected to each other by a flexible
5 sheet.

1 4. An electronic device as claimed in claim 2,
2 wherein a heat generating portion of a package or the like
3 mounted therein with said electrical circuit component and
4 said movable fin are connected to each other by a flexible
5 sheet.

1 5. An electronic device as claimed in claim 1,
2 wherein said movable fin is caused to protrude to the
3 outside of said sealed housing by a member that returns to
4 its original shape at a set temperature.

1 6. An electronic device as claimed in claim 2,
2 wherein said movable fin is caused to protrude to the
3 outside of said sealed housing by a member that returns to
4 its original shape at a set temperature.

1 7. An electronic device as claimed in claim 3,
2 wherein said movable fin is caused to protrude to the
3 outside of said sealed housing by a member that returns to
4 its original shape at a set temperature.

1 8. An electronic device as claimed in claim 4,
2 wherein said movable fin is caused to protrude to the
3 outside of said sealed housing by a member that returns to
4 its original shape at a set temperature.

1 9. An electronic device comprising:
2 a sealed housing;
3 an electrical circuit component in said sealed
4 housing; and
5 a bellows container with a variable internal
6 volume that is connected between a first hole in an upper

7 part of said sealed housing and a second hole in a lower
8 part thereof.

1 10. An electronic device comprising:
2 a sealed housing;
3 an electrical circuit component in said sealed
4 housing; and
5 an expandable/contractible balloon that is
6 connected between a first hole in an upper part of said
7 sealed housing and a second hole in a lower part thereof.

1 11. A heat radiation method for an electronic device
2 having a sealed housing, wherein, when an internal
3 temperature of said sealed housing having therein an
4 electrical circuit component rises, a movable fin is caused
5 to protrude to the outside of said sealed housing.

1 12. A heat radiation method for an electronic device
2 having a sealed housing as claimed in claim 11, wherein
3 said movable fin is caused to protrude through a guide hole
4 formed in said sealed housing, while keeping airtightness.

1 13. A heat radiation method for an electronic device
2 having a sealed housing as claimed in claim 11, wherein
3 heat of a package or the like mounted therein with said
4 electrical circuit component is conducted to said movable
5 fin by a flexible sheet.

1 14. A heat radiation method for an electronic device
2 having a sealed housing as claimed in claim 12, wherein
3 heat of a package or the like mounted therein with said
4 electrical circuit component is conducted to said movable
5 fin by a flexible sheet.

1 15. A heat radiation method for an electronic device
2 having a sealed housing as claimed in claim 11, wherein
3 said movable fin is caused to protrude by deformation of a
4 member due to a temperature, said member adapted to return
5 to its original shape.

1 16. A heat radiation method for an electronic device
2 having a sealed housing as claimed in claim 12, wherein
3 said movable fin is caused to protrude by deformation of a
4 member due to a temperature, said member adapted to return
5 to its original shape.

1 17. A heat radiation method for an electronic device
2 having a sealed housing as claimed in claim 13, wherein
3 said movable fin is caused to protrude by deformation of a
4 member due to a temperature, said member adapted to return
5 to its original shape.

1 18. A heat radiation method for an electronic device
2 having a sealed housing as claimed in claim 14, wherein

3 said movable fin is caused to protrude by deformation of a
4 member due to a temperature, said member adapted to return
5 to its original shape.

1 19. A heat radiation method for an electronic device
2 having a sealed housing, wherein, when an internal
3 temperature of said sealed housing having therein an
4 electrical circuit component rises, a bellows container
5 connected between a first hole in an upper part of said
6 sealed housing and a second hole in a lower part thereof
7 increases its internal volume.

1 20. A heat radiation method for an electronic device
2 having a sealed housing, wherein, when an internal
3 temperature of said sealed housing having therein an
4 electrical circuit component rises, an
5 expandable/contractible balloon connected between a first
6 hole in an upper part of said sealed housing and a second
7 hole in a lower part thereof increases its internal volume.

1 21. A sealed housing of an electronic device,
2 comprising:
3 a guide hole; and
4 a movable fin that protrudes to the outside
5 through said guide hole depending on a rise in internal
6 temperature of said sealed housing.

1 22. A sealed housing of an electronic device as
2 claimed in claim 21, wherein said movable fin has
3 airtightness means between itself and said guide hole.

1 23. A sealed housing of an electronic device as
2 claimed in claim 21, further comprising a flexible sheet
3 connecting between a heat generating portion mounted in
4 said sealed housing and said movable fin.

1 24. A sealed housing of an electronic device as
2 claimed in claim 22, further comprising a flexible sheet
3 connecting between a heat generating portion mounted in
4 said sealed housing and said movable fin.

1 25. A sealed housing of an electronic device as
2 claimed in claim 21, wherein said movable fin is caused to
3 protrude to the outside by a member that returns to its
4 original shape at a set temperature.

1 26. A sealed housing of an electronic device as
2 claimed in claim 22, wherein said movable fin is caused to
3 protrude to the outside by a member that returns to its
4 original shape at a set temperature.

1 27. A sealed housing of an electronic device as
2 claimed in claim 23, wherein said movable fin is caused to
3 protrude to the outside by a member that returns to its

4 original shape at a set temperature.

1 28. A sealed housing of an electronic device as
2 claimed in claim 24, wherein said movable fin is caused to
3 protrude to the outside by a member that returns to its
4 original shape at a set temperature.

1 29. A sealed housing of an electronic device,
2 comprising:
3 a first hole in an upper part of said sealed
4 housing;
5 a second hole in a lower part of said sealed
6 housing; and
7 a bellows container with a variable internal
8 volume that is connected between said first hole and said
9 second hole.

1 30. A sealed housing of an electronic device,
2 comprising:
3 a first hole in an upper part of said sealed
4 housing;
5 a second hole in a lower part of said sealed
6 housing; and
7 an expandable/contractible balloon that is
8 connected between said first hole and said second hole.